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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
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Complete if Known	
Application Number	10/607,738
Filing Date	June 26, 2003
First Named Inventor	Houle, Sabina
Group Art Unit	1725
Examiner Name	Kiley Stoner
Attorney Docket No: 884.832US1	

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EXAMINER

[Signature]

DATE CONSIDERED 5/18/05